



# News Release

## **Unisem Announces Exhibits at Upcoming March Conferences**

**Sunnyvale, 12 March 2015** – Unisem, a global provider of semiconductor assembly and test services, today announced that it will be exhibiting at the iMAPS 11<sup>th</sup> International Conference and Exhibition on Device Packaging on March 17-18 in Fountain Hills, AZ.

The company will also participate in Semicon China on March 17-19 in Shanghai, China but will not be exhibiting.

### **About Unisem**

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; Batam, Indonesia; and Sunnyvale, USA. Unisem is headquartered in Kuala Lumpur, Malaysia.

For additional information on Unisem, please visit: [www.unisemgroup.com](http://www.unisemgroup.com). Follow Unisem on [Twitter](#) and on [LinkedIn](#).

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